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**Flexible Epoxy Adhesive**  
**Solvent Free Paste**  
**Tough and Reworkable**  
**Ambient Temperature Storable**

**IDEAL FOR:**

- Large Area Bonding
- Mismatched CTE Bonding
- Substrate Attach

**DESCRIPTION:**

ME7150 is a tough and yet flexible epoxy adhesive. It has very low ionic impurities and good electrical insulation. It has outstanding adhesion to most substrates having vastly different CTE's. When used as an adhesive, ME7150 is suitable for bonding large area substrates and components. The thixotropic paste (T.I. > 3) may be stored at ambient temperature for one month.

It can be readily reworked at 80-100°C.

**AVAILABILITY:**

ME7150 is available in syringes for automatic needle dispense applications or in jars. Both viscosity and thixotropic index can be modified to your specific needs.

**APPLICATION PROCEDURES:**

- ( 1 ) Thaw for 30 minutes before opening jar.
- ( 2 ) Dispense adhesive onto clean substrate.
- ( 3 ) Cure according to one of the recommended schedules.

**CAUTION:** This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details  
 The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

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**PRIMA-BOND**  
**ME7150**

**TYPICAL PROPERTIES\***

Electrical Resistivity ( 150 °C/ 10 minute )	>1x10 <sup>14</sup> ohm-cm
Dielectric Strength (Volts/mil)	>750
Glass Transition Temp.(°C)	-25 ±10%
Current Carrying Capabilities	N/A
Lap-Shear Strength	>1000 psi >6.9 N/mm <sup>2</sup>
Device Push-off Strength	>1800 psi >12.4 N/mm <sup>2</sup>
Hardness (Type)	80 (A) ±10%
Cured Density (gm/cc)	1.2 ±10%
Thermal Conductivity	1.2 Btu-in/hr-ft <sup>2</sup> -°F ±10% 0.17 W/m-°C ±10%
Linear Thermal Expansion Coeff. (ppm/°C)	180 ±15%
Maximum Continuous Operation Temp. (°C)	<150
Avg. Viscosity(0.5 rpm, 25°C)	50,000 cp ±20%

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**CURE SCHEDULES:**

<u>Temperature</u>	<u>Time</u>	<u>Pressure</u>
80°C	8 hr	
100°C	4 hr	
125°C	2 hr	
150°C	1 hr	

Pot life is 5 days @ 25°C

**SHELF LIFE:**

<u>Storage temperature</u>	<u>Shelf Life</u>
-40°C	1 yr